

Docket No.: MAS-FIN-193

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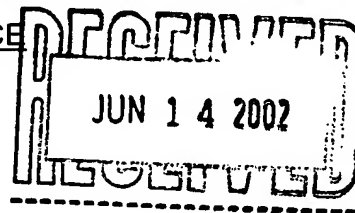
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By: [Signature]

Date: February 28, 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Harry Hedler et al.
Applic. No. : 10/022,226
Filed : December 17, 2001
Title : Electronic Component with Flexible Bonding Pads and Method of Producing a Component
Art Unit : 2814



INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents and Trademarks,
Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications are submitted herewith:

United States Patent No. 4,740,700 (Shaham et al.), dated April 26, 1988;

United States Patent No. 5,196,371 (Kulesza et al.), dated March 23, 1993;

United States Patent No. 5,783,465 (Canning et al.), dated July 21, 1998;

German Published, Non-Prosecuted Patent Application DE 196 39 934 A1 (Jansseune et al.), dated April 9, 1998, method for flip chip bonding a semiconductor chip;

Japanese Patent Abstract JP 0 010 281 792 A (Inoue et al.), dated May 9, 1988;

International Publication WO 98/50950 (Ichitani et al.), dated November 12, 1998;

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English translation of International Preliminary Examination Report dated September 25, 2000.

If no translation of pertinent portions of any foreign language patents or publications mentioned above is included with the aforementioned copies of those applications, patents and/or publications, it is because no existing translation is readily available to the applicant.

Respectfully submitted,

For Applicants

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Date: February 28, 2002

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